

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6260021

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JUNICHI SOMEI	08/05/2020
KENJI HATAZAWA	08/05/2020
TOYOHIRO HARAZONO	08/05/2020
HIROHIKO UEDA	08/05/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KALTECH CORPORATION
<b>Street Address:</b>	3-3-7, BAKUROUMACHI, CHUO-KU
<b>Internal Address:</b>	10TH FLOOR, BUILDING HIROTAKE
<b>City:</b>	OSAKA-SHI, OSAKA
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	5410059
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16997546
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(612)455-3801
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<b>Email:</b>	sfuruya@hsml.com
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<b>Address Line 2:</b>	SUITE 2700
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402-1683
<b>ATTORNEY DOCKET NUMBER:</b>	20488.0035US01
<b>NAME OF SUBMITTER:</b>	MASAKO YOSHIDA
<b>SIGNATURE:</b>	/Masako Yoshida/
<b>DATE SIGNED:</b>	08/20/2020
<b>Total Attachments: 2</b>	

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**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS,

1. **Junichi SOMEI** having an address of c/o KALTECH CORPORATION, 10th Floor, Building Hirotake, 3-3-7, Bakuroumachi, Chuo-ku, Osaka-shi, Osaka 5410059, Japan
2. **Kenji HATAZAWA** having an address of c/o KALTECH CORPORATION, 10th Floor, Building Hirotake, 3-3-7, Bakuroumachi, Chuo-ku, Osaka-shi, Osaka 5410059, Japan
3. **Toyohiro HARAZONO** having an address of c/o KALTECH CORPORATION, 10th Floor, Building Hirotake, 3-3-7, Bakuroumachi, Chuo-ku, Osaka-shi, Osaka 5410059, Japan
4. **Hirohiko UEDA** having an address of c/o KALTECH CORPORATION, 10th Floor, Building Hirotake, 3-3-7, Bakuroumachi, Chuo-ku, Osaka-shi, Osaka 5410059, Japan

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on \_\_\_\_\_, entitled **WALL ATTACHMENT SYSTEM**, and which has been given application serial number \_\_\_\_\_;

and

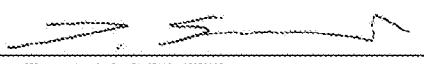
WHEREAS **KALTECH CORPORATION** (hereinafter "ASSIGNEE") a corporation organized under the laws of Japan and having an office and place of business at 10th Floor, Building Hirotake, 3-3-7, Bakuroumachi, Chuo-ku, Osaka-shi, Osaka 5410059, Japan wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

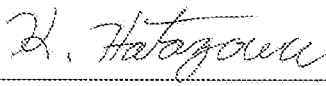
NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

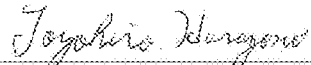
THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

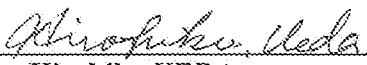
THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

 05 Aug. 2020  
1. **Junichi SOMEI** Date

 5 Aug. 2020  
2. **Kenji HATAZAWA** Date

 5 Aug. 2020  
3. **Toyohiro HARAZONO** Date

 5 Aug. 2020  
4. **Hirohiko UEDA** Date